

In response to the Office Action mailed January 2, 2004, Applicant respectfully requests reconsideration of the above-identified application in view of the following amendments and remarks.

AMENDMENTS TO THE CLAIMS

Please amend the claims as follows:

CLAIM 1 (Original)

- 1 An enclosure apparatus comprising:
- 2 a substrate having first and second planar surfaces and defining an aperture in said
- 3 substrate through said planar surfaces;
- 4 a die disposed within said aperture, said die having first and second planar surfaces with
- 5 conductive bonding pads on said first surface of said die;
- 6 a first layer of glass disposed over said first surfaces of said substrate and said die, said
- 7 glass omitted from said bonding pads;
- 8 a second layer of glass disposed over said second surface of said substrate and at least a
- 9 portion of said second surface of said die; and
- 10 conductive traces disposed on said first layer of glass and operably coupled to said
- 11 conductive bonding pads of said die and extending to an outer periphery of said first layer of
- 12 glass.

CLAIM 2 (Currently amended)

- 1 The enclosure of claim 1 wherein said enclosure is interconnected at said outer periphery of said
- 2 enclosure through a pressure-fit interconnect.

CLAIM 3 (Currently amended)

- 1 The [flexible] enclosure of claim 2 wherein said conductive traces are disposed from said die to
- 2 opposite sides of said enclosure.

CLAIM 4 (Original)

- 1 The enclosure of claim 1 further including a metallic heat sink disposed on said second surface
- 2 of said die.

CLAIM 5 (Original)

- 1 The enclosure of claim 3 wherein said substrate is silica.

CLAIM 6 (Currently amended)

- 1 The enclosure of claim 1 wherein one or more of said layers of said glass [flow into] fill a void
- 2 between said substrate and said die.

CLAIM 7 (Original)

- 1 An enclosure apparatus comprising:
- 2 a flexible substrate, said substrate having first and second planar surfaces and defining an
- 3 aperture in said substrate through said planar surfaces;

4 a die disposed within said aperture, said die having first and second planar surfaces with
5 conductive bonding pads on said first surface of said die;

6 a first layer of glass disposed over said first surfaces of said substrate and said die, said
7 glass omitted from said bonding pads;

8 a second layer of glass disposed over said second surface of said substrate and at least a
9 portion of said second surface of said die; and

10 conductive traces disposed on said first layer of glass and operably coupled to said
11 conductive bonding pads of said die and extending to an outer periphery of said first layer of
12 glass.

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CLAIM 8 (Currently amended)

1 The enclosure of claim 7 wherein said enclosure is interconnected at said outer periphery of said
2 enclosure through a pressure-fit interconnect.

CLAIM 9 (Original)

1 The enclosure of claim 7 wherein said conductive traces are disposed from said die to opposite
2 sides of said enclosure.

CLAIM 10 (Original)

- 1 The enclosure of claim 8 wherein one or more of said planar surfaces are made arcuate when
- 2 said enclosure is interconnected.

CLAIM 11 (Currently amended)

- 1 The enclosure of claim 10 wherein said enclosure is interconnected at said outer periphery of
- 2 said enclosure through a pressure- fit interconnect.

CLAIM 12 (Original)

- 1 The enclosure of claim 11 wherein said conductive traces are disposed from said die to opposite
- 2 sides of said enclosure.

CLAIM 13 (Original)

- 1 The enclosure of claim 7 further including a metallic heat sink disposed on said second surface
- 2 of said die.

CLAIM 14 (Original)

- 1 The enclosure of claim 7 wherein said flexible substrate is silica.

CLAIM 15 (Currently amended)

1 The enclosure of claim 7 wherein one or more of said layers of said glass [flow into] fill a void
2 between said substrate and said die.

CLAIM 16 (Original)

1 A flexible enclosure apparatus comprising:
2 a flexible silica substrate, said silica substrate having first and second planar surfaces and
3 defining an aperture in said substrate through said planar surfaces;
4 a die disposed within said aperture, said die having first and second planar surfaces
5 substantially coplanar with said first and second surfaces of said silica substrate, respectively,
6 said die having conductive bonding pads on its said first surface;
7 a first layer of glass disposed over said first surfaces of said substrate and said die; said
8 glass omitted from said bonding pads;
9 a second layer of glass disposed over said second surface of said substrate and at least a
10 portion of said second surface of said die; and
11 conductive traces disposed on said first layer of glass and operably coupled to said conductive
12 bonding pads of said die and extending to an outer periphery of said first layer of glass, said
13 conductive traces making a pressure-fit interconnect at said outer periphery of said enclosure
14 when said enclosure is interconnected and wherein one or more of said planar surfaces are made
15 arcuate when said enclosure is interconnected.

CLAIM 17 (Original)

- 1 The flexible enclosure of claim 16 wherein said conductive traces are disposed from said die to
- 2 opposite sides of said enclosure.

CLAIM 18 (Original)

- 1 The flexible enclosure of claim 16 further including a metallic heat sink disposed on said second
- 2 surface of said die.

CLAIM 19 (Currently amended)

- 1 The enclosure of claim 16 wherein one or more of said layers of said glass [flow into] fill a void
- 2 between said substrate and said die.